

Die bonder---HAD8613-A





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Descriptions:

1. High precision linear motor and voice coil motor drive

2. Using the stop shooting visual positioning of the central turntable, achieving X, Y through the precise adjustment mechanism of the central turntable, θ Accuracy correction avoids the offset and rotation of the chip during blue film separation.

3. A servo motor and precision screw structure are used to drive the chip search platform (X/Y) to ensure crystal search accuracy. A linear motor is used to drive the fixed crystal PCB platform (B/C) to ensure PCB pad positioning accuracy and speed.

4. Adopting vacuum crystal leakage detection and automatically setting the pressure of the solid crystal welding head.

5. Adopting a crystal frame 360 ° rotation structure, it can automatically recognize and correct chip polarity.

6. Equipped with the structure of automatic blue film changing and automatic mold expanding, which improves production efficiency and saves labor costs.

7. Equipped with a dual dispensing system (adhesive disc sticking), and can also be equipped with an optional dispensing function for the glue cylinder.

8. The industrial computer controls the operation of equipment, simplifying the operation of automation equipment.

9. Powerful software functions ensure device data storage and MES operation.

10. Equipped with PCB platform fixture import coordinate production.

11. The operation interface is available in both Chinese and English.





Overall dimensions: Length*Width*Height= 2115*1380*1980(mm) Overall dimensions: Length*Width*Height = 1600*1420*1480(mm) (without indicator and console)





Schematic diagram of the plane working area



Secondary correction transfer station



Precise electric adjustment platforms and electric angle correction structures are adopted to realize fast positioning and angle correction functions.





Adopting a high-precision linear direct drive motor displacement platform and double bond head structure, combined with a secondary correction transfer platform, to achieve high-precision crystal solidification operation.

OUTHERN ACHINERY Glue dispensing assembly



Adopting an independent double dispensing arm and rotating glue cup structure can achieve a uniform and fast dispensing function.





Using a linear direct drive motor to drive the fixture platform, can achieve rapid and accurate positioning of the solder pad position.



Loading and unloading assembly



Adopting a precision lifting magazine platform and pushing rob mechanism, the magazine and PCB can be connected for loading and unloading and can accommodate 2 magazines.





Adopting a precision screw module and pneumatic clamp structure can achieve stable and fast clamping of crystal rings.



Using high-performance servo motors and precision screw mechanisms to drive the XY (Wafer) platform, it can achieve a fast and accurate crystal finding function; At the same time, the Wafer mechanism also has an automatic film expansion function, which can meet the automatic loading and film expansion of 8-inch wafers (iron films). Simultaneously compatible with smaller crystal rings (configured according to customer requirements)



Crystal replacement shifting mechanism



Using a precision lifting crystal ring magazine platform and crystal ring transferring together, achieved the automatic and non-stop replacement of crystal rings.



HAD8613-A technical parameters

	Items	Description	Parameters
1		Cycle time	1200ms(Depends on chip size and holder)
2		Die Accuracy	$\pm 10\mu$ m
	System Function	Die Rotation	±1°
		Die angle	0° or 90°
3		СРК	≥1.33
4	Die XY Workbench	Chip size	3mi1×5mi1-120mi1×120mi1 (0.076mm*0.127mm-3.0mm*3.0mm)
5		Max Die Ring size	8" (203mm) External diameter
6		Max chip area	7.6" (194mm) Expanded
7		Chip XY platform encoder accuracy	23 <u>bit</u>
8		Thimble Z stroke	80mil (2mm)
9	Image Recognition System	Gray scale	256 Level Grey
10		Resolution	720×540 Pixels
11		Image recognition accuracy	±3µm @50mil (Observation Range)
12		Crystal absorbing bonder head	Linear motor drive
		Die bonder head	Voice coil motor drive
	Crystal absorbing swing arm system	Crystal absorbing bonder reading head resolution	1 µ m
13		Crystal absorbing pressure	30g—250g adjustable



14		PCB holder (includes carrier) overall dimension	Length: 100mm-260mm. Width: 60mm-150mm.
15	Loading Workbench	PCB holder working range (L*M) Max	250mm*150mm
16		PCB platform reading head Resolution	0.02mil (0.5µm)
17		Power Supply	220V AC±5%/50HZ
18		Air supply	0.5MPa (MIN)
19	Facilities Needed	Rated power	1120 W
20		Air consumption	40L/min (instantaneous) 10L/min (working)
21		Overall dimension L*W*H mm	1600mm*1420mm*1840mm
22	Volume and Weight	Weight	Approx. 1500 Kg









Best After-sales service

- 7x24 Worldwide Support
- Free Installation/ Training
- 1 day lead-time (spare parts)
- 1 Month customize solution



WELCOME INQUIRY

